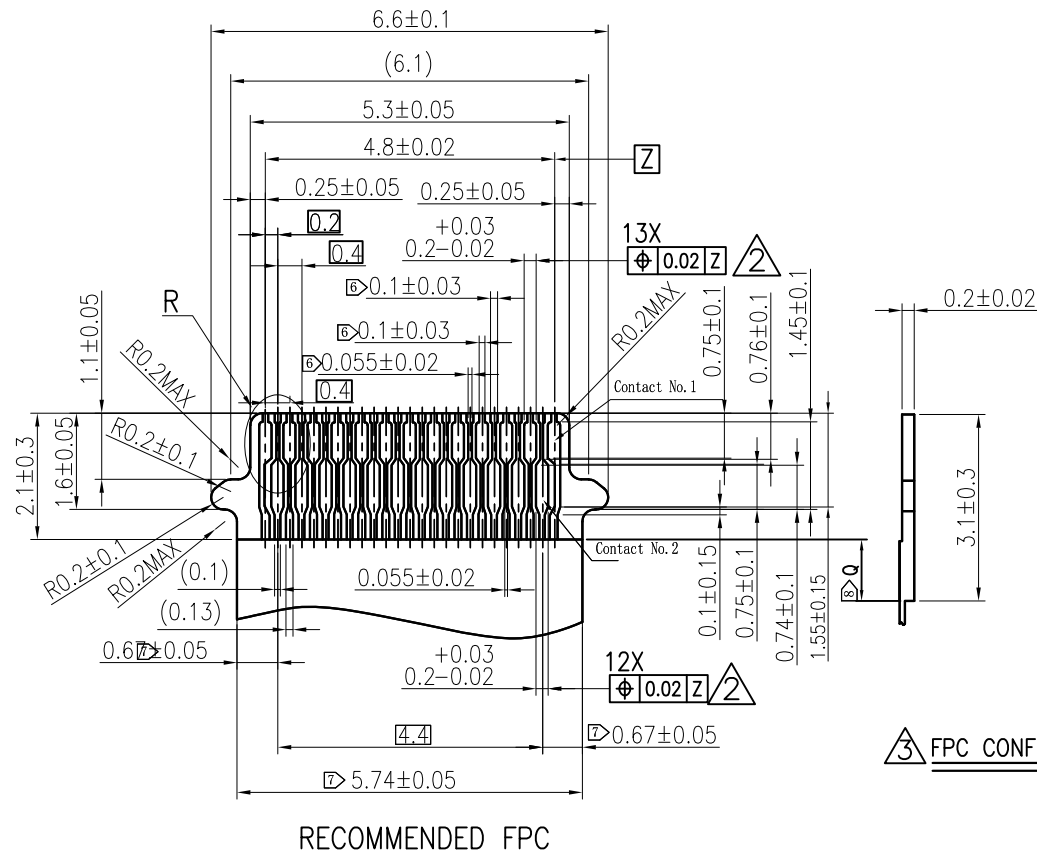
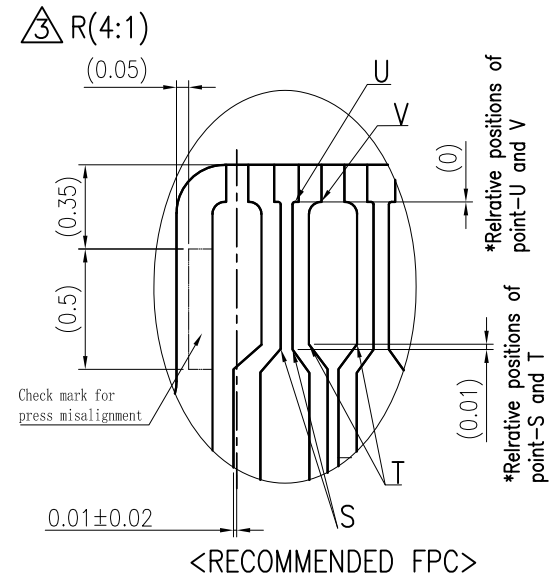


F		F	
修订 REV	标记 MARK	修改摘要 REVISION DESCRIPTION	签名 SIGNATURE
AO		NEW DWG	



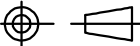
NOTE ⑥ Shows recommended dimension when lead for plating is required.
 ⑦ Indicated tolerance is applicable to the exposed conductor.
 ⑧ Dimension Q must be 0.5mm minimum.



△3 FPC CONFIGURATION (REFERENC EXAMPLE) (FPC)

MATERIAL NAME	MATERIAL	THICKNESS(μm)
COVERING FILM LAYER POLYIMIDE	1 mil	25
COER ADHESIVE		25
SURFACE TREATMENT	1 μm TO 6 μm NICKEL UNDERPLATED 0.2 μm GOLD PLATED.	(4)
COPPER FOIL	Cu 1/3 oz	12
BASE ADHESIVE	HEAT-HARDENED ADHESIVE	No adhesion material
BASE FILM	POLYIMIDE 1 mil	25
REINFORCEMENT MATERIAL ADHESIVE	HEAT-HARDENED ADHESIVE	30
STIFFENER	POLYIMIDE 5 mil	125

- (1)Temperature: -55℃~85℃
- (2)Relative humidity: ≤90% RH
- (3)Rating: AC/DC 30V 0.2A
- (4)Contact Resistance:≤100m ohm
- 5)Insulation Resistance:≥50M ohm
- (6)Withstand Voltage: AC 90V for 1min

		深圳市华德共创科技有限公司 Shenzhen Huade co-create Technology Co., LTD 电话: 0755-27111216 传真: 0755-29940187				
~TOLERANCES~ UNLESS OTHERWISE SPECIFIED 公差参数表				TITLE: 产品名称: 0.2MM间距FPC连接器		
X.X	±0.30	X.X*	±3*	APPD: 核准: 谢亮		
X.XX	±0.30	X.XX*	±2*	PART NO: 产品编号: HDGC0200WR-S-25P		
X.XXX	±0.10	X.XXX*	±1*	CHECK: 校对: 王建业		
DRAW: 绘图: 黄艳兰				DATE	SCALE	UNIT
					1:1	mm
				CODE NUMBER A001		